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PATENT APPLICATION

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q62228

Yoshihisa FURUTA, et al.

Appln. No.: 09/719,422

Group Art Unit: 1733

Confirmation No.: 7788

Examiner: Barbara J. MUSSER

Filed: December 12, 2000

For: METHOD OF RESIN ENCAPSULATING SEMICONDUCTOR CHIP AND PRESSURE-SENSITIVE ADHESIVE TAPE FOR ADHESION TO LEADFRAME AND THE LIKE

AMENDMENT UNDER 37 C.F.R. § 1.111

Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated June 5, 2002, review and reconsideration are requested in view of the following amendments and remarks. Please amend the above-identified application as follows:

IN THE SPECIFICATION:

Page 3 of the specification, paragraph 2, please delete that paragraph and add the following new paragraph.

a
Fig. 1A shows a leadframe with an pressure-sensitive adhesive tape adhered thereto, wherein numeral 1 is a leadframe having a group of units each having a large number of stitches 11 arranged around the device hole. Numeral 2 is an pressure-sensitive adhesive tape affixed to the leadframe 1, whose thermal shrinkage on resin encapsulating is controlled to 3% or less,